



MEDIA ALERT

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USB Implementers Forum Announces Tokyo SuperSpeed USB Developers Conference

Conference to Showcase First SuperSpeed USB Interoperability Demo

WHAT: The USB Implementers Forum has announced it will hold a SuperSpeed USB Developers Conference in Tokyo, featuring the world's first demonstration of SuperSpeed USB interoperability between a PC host and flash storage device from different companies. The SuperSpeed USB Developers Conference will also provide attendees the opportunity to hear directly from the creators of the USB 3.0 specification, which is the technical map for device manufacturers to bring SuperSpeed USB technology to the market. Keynote speakers will address advancements offered by the new technology, and attendees will obtain important information on best practices for incorporating SuperSpeed USB into their product roadmaps.

In addition to the technical sessions, an exhibit area will showcase the latest SuperSpeed USB developments including the interoperability demonstration.

WHEN: May 20-21, 2009

Members of the media and industry analyst communities are welcome to attend a comprehensive media update. Please email press@usb.org regarding media event attendance.

WHERE: Four Seasons Hotel Tokyo at Chinzan-so
Tokyo, Japan

WHO: The conference is hosted by the [USB Implementers Forum](#).

REGISTER: To register for the Developers Conference, please visit the [USB-IF Web site](#).

Members of the media and analyst communities can email attendance inquiries to press@usb.org.

About SuperSpeed USB

SuperSpeed USB brings significant performance enhancements to the ubiquitous USB standard, while remaining compatible with the billions of USB enabled devices currently deployed in the market. SuperSpeed USB will deliver 10x the data transfer rate of Hi-Speed USB, as well as improved power efficiency.

The USB 3.0 specification was developed by the USB 3.0 Promoter Group which consists of Intel Corporation, Hewlett-Packard Company, Microsoft Corporation, NEC Corporation, ST-Ericsson and Texas Instruments.

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